

Multifunctional 64-/128-bit OTP RFID IDIC ATA5575M1

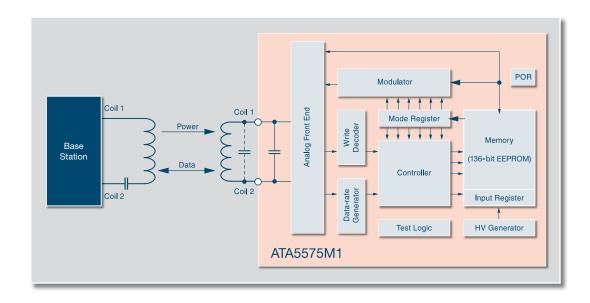
Atmel® offers a broad range of RFID devices for contactless read/write RF identification systems, delivered as die on wafer, die in tray, die on tape, micromodule, or complete transponder in a plastic package. Our low-frequency IDIC® products (100 to 150 kHz) with different security levels are flexible for all kinds of applications, easy to design-in and well-matched.

The LF transponder IDIC ATA5575M1 is a new member of Atmel's broad RFID transponder family, and has been optimized for next-generation access control systems as used in hotel rooms, engineering departments, offices, time recording systems and parking lots as well as for customer loyalty and membership cards.

The ATA5575M1 provides OTP (one-time programmable) functionality which simplifies the production process and reduces time-to-market.

Features

- Contactless 100 kHz to 150 kHz Identification IC (IDIC)
- OTP (One-time Programmable) Functionality
- Mega Pads with/without Gold Bumps
- Compatible Unique Format
- On-chip Capacitor 250 pF or 330 pF, Trimmed
- 64-/128-bit User Memory
- 64-bit Unique ID, Pre-programmed Twice in Memory, Overwritable
- Data Rate RF04/64
- ASK Modulation, Manchester Coding
- Operating Range of -40°C to +85°C







Applications

- All Applications Using Unique Format
- Access Control ISO Cards, Key Fobs, and Coins
- Asset Management
- Manufacturing and Logistics
 - Material Handling
 - Recycling
 - Cylinder Tracking

Unique Structure

'1' '1' '1'	'1'	'1'	'1'	'1'	'1'	'1'	9 Header Bits
bit 1	Digit 0	D00	D01	D02	D03	PR0	
	Digit 1	D10	D11	D12	D13	PR1	⊕ ≤
byte 0 to 3	Digit 2	D20	D21	D22	D23	PR2	even row parity bit per digit
	Digit 3	D30	D31	D32	D33	PR3	WO W
	Digit 4	D40	D41	D42	D43	PR4	pari:
	Digit 5	D50	D51	D52	D53	PR5	ty b
byte 4 to 7	Digit 6	D60	D61	D62	D63	PR6	it pe
	Digit 7	D70	D71	D72	D73	PR7	94 0
	Digit 8	D80	D81	D82	D83	PR8	g:
	Digit 9	D90	D91	D92	D93	PR9	
		PC0	PC1	PC2	PC3	'0'	
		even	colum	n parit	bit 64		

Support Tools

- Application Kit ATA2270-EK1
- Datasheet
- Qual Packs



Memory Mapping

18	
Configuration Data	Byte 16
User Data	Byte 15
User Data	Byte 14
User Data	Byte 13
User Data	Byte 12
User Data	Byte 11
User Data	Byte 10
User Data	Byte 9
User Data	Byte 8
User Data	Byte 7
User Data	Byte 6
User Data	Byte 5
User Data	Byte 4
User Data	Byte 3
User Data	Byte 2
User Data	Byte 1
User Data	Byte 0

Not transmitted

Headquarters

Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131 USA

Tel: (1) 408 441-0311 Fax: (1) 408 487-2600

International

Atmel Asia

Unit 01-05 & 16, 19F BEA Tower, Millenium City 5 418 Kwun Tong Road Kwun Tong, Kowloon Hong Kong

Tel: (852) 2245-6100 Fax: (852) 2722-1369

Atmel Europe

Le Krebs 8, Rue Jean-Pierre Timbaud BP 309 78180 Montigny-le-Bretonneux

Tel: (33) 1-30-60-70-00 Fax: (33) 1-30-60-71-11

Atmel Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033

Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

Product Contact

Product Line

rfid@atmel.com

Literature Requests

www.atmel.com/literature

Web Site www.atmel.com

Ordering Information

Part Number	On-Chip Capacity Value pF ccc	Package	Description
ATA5575M1ccc-xxx	250/330	DDB	6" Sawn Wafer on Foil with Ring, Thickness 150 μm (Approx. 6 mil)
		DBB	6" Sawn Wafer on Foil with Ring and Au Bumps 25 μm, Thickness 150 μm (Approx. 6 mil) Plus 25 μm Bumps
		DDW 1)	6" Wafer, Thickness 280 μm (Approx. 11 mil)
		DDT 1)	Die in Waffle Pack, Thickness 280 μm (Approx. 11 mil)
		DBN 1)	Die with Au Bumps 25 μm on Sticky Tape, Thickness 280 μm (Approx. 11 mil)
		DBQ 1)	Die with Au Bumps 25 μm on Blister Tape, Thickness 280 μm (Approx. 11 mil)

1) On request

© 2009 Atmel Corporation. All rights reserved.

Atmel®, Atmel logo and combinations thereof, IDIC®, and others are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.

Rev.: 9021A-RFID-11/09/01M

